

# EMK13H2J-30.0018M TR



## ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 3.3Vdc 4 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD) 30.0018MHz  $\pm 50$ ppm over -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

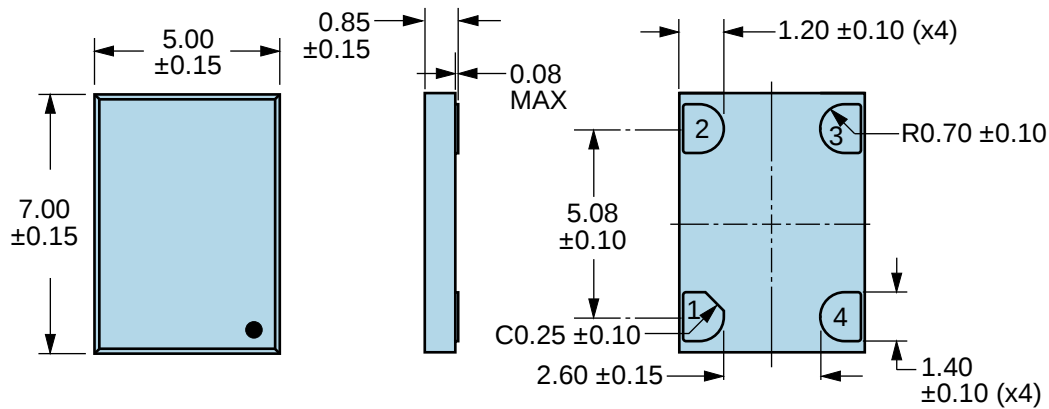
|                                 |                                                                                                                                                                                                                                                                          |
|---------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency               | 30.0018MHz                                                                                                                                                                                                                                                               |
| Frequency Tolerance/Stability   | $\pm 50$ ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration) |
| Aging at 25°C                   | $\pm 1$ ppm Maximum First Year                                                                                                                                                                                                                                           |
| Supply Voltage                  | 3.3Vdc $\pm 10\%$                                                                                                                                                                                                                                                        |
| Input Current                   | 25mA Maximum                                                                                                                                                                                                                                                             |
| Output Voltage Logic High (Voh) | 90% of Vdd Minimum (IOH=-8mA)                                                                                                                                                                                                                                            |
| Output Voltage Logic Low (Vol)  | 10% of Vdd Maximum (IOL=+8mA)                                                                                                                                                                                                                                            |
| Rise/Fall Time                  | 2nSec Maximum (Measured from 20% to 80% of waveform)                                                                                                                                                                                                                     |
| Duty Cycle                      | 50 $\pm 5$ (%) (Measured at 50% of waveform)                                                                                                                                                                                                                             |
| Load Drive Capability           | 15pF Maximum                                                                                                                                                                                                                                                             |
| Output Logic Type               | CMOS                                                                                                                                                                                                                                                                     |
| Output Control Function         | Power Down (Disabled Output: Logic Low)                                                                                                                                                                                                                                  |
| Output Control Input Voltage    | +0.7Vdd Minimum or No Connect to Enable Output, +0.3Vdd Maximum to Disable Output                                                                                                                                                                                        |
| Standby Current                 | 50 $\mu$ A Maximum (Disabled Output: Logic Low)                                                                                                                                                                                                                          |
| Peak to Peak Jitter (tPK)       | 250pSec Maximum, 100pSec Typical                                                                                                                                                                                                                                         |
| Start Up Time                   | 50mSec Maximum                                                                                                                                                                                                                                                           |
| Storage Temperature Range       | -55°C to +125°C                                                                                                                                                                                                                                                          |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                                                    |
|------------------------------|--------------------------------------------------------------------|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 2, HBM 2000V                       |
| Flammability                 | UL94-V0                                                            |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition G, 30,000G                     |
| Moisture Resistance          | MIL-STD-883, Method 1004                                           |
| Moisture Sensitivity Level   | J-STD-020, MSL 1                                                   |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K                               |
| Resistance to Solvents       | MIL-STD-202, Method 215                                            |
| Solderability                | MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only) |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B                              |
| Thermal Shock                | MIL-STD-883, Method 1011, Condition B                              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A, 20G                         |



### MECHANICAL DIMENSIONS (all dimensions in millimeters)

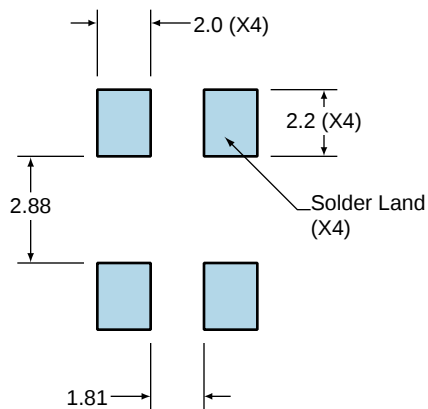


| PIN | CONNECTION             |
|-----|------------------------|
| 1   | Power Down (Logic Low) |
| 2   | Ground                 |
| 3   | Output                 |
| 4   | Supply Voltage         |

| LINE | MARKING                                             |
|------|-----------------------------------------------------|
| 1    | XXXXXX<br>XXXXXX=Ecliptek<br>Manufacturing Lot Code |

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

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OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.01  $\mu\text{F}$  ceramic bypass capacitor in parallel with a 0.1  $\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

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## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

|                                     |                                      |
|-------------------------------------|--------------------------------------|
| Ts MAX to TL (Ramp-up Rate)         | 3°C/Second Maximum                   |
| Preheat                             |                                      |
| - Temperature Minimum (Ts MIN)      | 150°C                                |
| - Temperature Typical (Ts TYP)      | 175°C                                |
| - Temperature Maximum (Ts MAX)      | 200°C                                |
| - Time (ts MIN)                     | 60 - 180 Seconds                     |
| Ramp-up Rate (TL to TP)             | 3°C/Second Maximum                   |
| Time Maintained Above:              |                                      |
| - Temperature (TL)                  | 217°C                                |
| - Time (tL)                         | 60 - 150 Seconds                     |
| Peak Temperature (TP)               | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C                        |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds                      |
| Ramp-down Rate                      | 6°C/Second Maximum                   |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                    |
| Moisture Sensitivity Level          | Level 1                              |

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## Recommended Solder Reflow Methods



## Low Temperature Infrared/Convection 240°C

T<sub>S</sub> MAX to T<sub>L</sub> (Ramp-up Rate) 5°C/Second Maximum

### Preheat

- Temperature Minimum (T<sub>S</sub> MIN) N/A
- Temperature Typical (T<sub>S</sub> TYP) 150°C
- Temperature Maximum (T<sub>S</sub> MAX) N/A
- Time (t<sub>s</sub> MIN) 60 - 120 Seconds

Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>) 5°C/Second Maximum

### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C
- Time (t<sub>L</sub>) 200 Seconds Maximum

Peak Temperature (T<sub>P</sub>) 240°C Maximum

Target Peak Temperature (T<sub>P</sub> Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (t<sub>p</sub>) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

## Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

## High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.